Supporting information for

Facile preparation of monodisperse Cu@Ag core–shell nanoparticles for conductive ink in printing electronics

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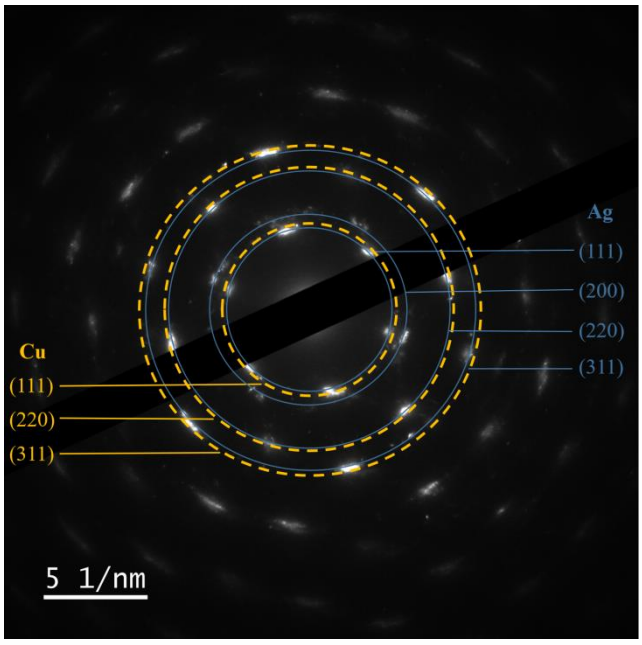

Figure S1. SAED pattern of Cu@Ag core-shell nanoparticles.

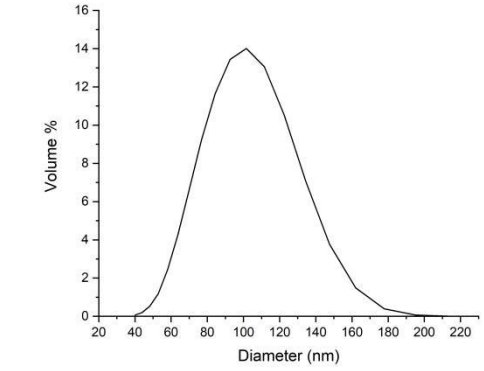

Figure S2. Size distribution of Cu@Ag nanoparticles according to DLS.

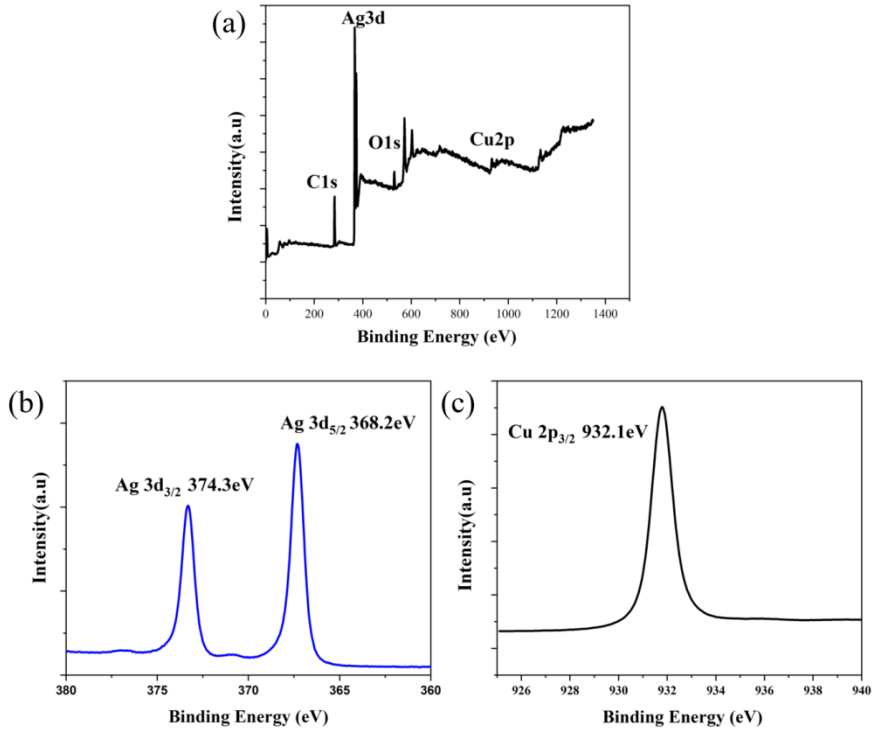

Figure S3. (**a**) survey spectra, (**b**) Ag 3d spectra, (**c**) Cu 2p3/2 spectra.

XPS analysis was further conducted to characterize the element composition of the different valence states of Cu–Ag core–shell nanoparticle. Figure S3 clearly illustrates that the binding energies of Cu 2p3/2, Ag 3d5/2 and Ag 3d3/2 were 932.1eV, 368.2eV and 374.3eV, respectively, demonstrating the presence of elementary Cu(0) and Ag(0).